IEEE 802.3 NEA Ad hoc Meeting – IEEE 802.3 "Ethernet for AI" Assessment
24 Feb 2026 Electronic Meeting - "Fiber for AI" Workshop

Unapproved Meeting Minutes, prepared by John D'Ambrosia
Session called to order at 9:00 am ET (all times ET), 24 Feb 2026

Meeting called to order by John D'Ambrosia, Chair - IEEE 802.3 NEA "Ethernet for AI" Assessment

Chair gave the meeting introduction.

Chair reminded everyone to sign into IMAT, which would be used for tracking attendance.
Chair noted he would also use zoom participants list for tracking attendance.

Presentation #1   **Agenda and General Information**
Presenter   John D'Ambrosia
URL   https://www.ieee802.org/3/ad_hoc/E4AI/public/26_0224/agenda_e4ai_a_260224.pdf

Agenda – chair asked if there were any comments on the agenda. There were none. Chair asked if there were any objections to the agenda, there were none, and the agenda was considered approved by unanimous consent.

Chair noted background on NEA can be found in Appendix. Any individual with questions about the group should contact him or Jon Lewis, IEEE 802.3 NEA Chair.

Chair presented Slide #4 that includes a reminder for all meeting participants should to review the following IEEE SA policies prior to participation in the meeting teleconference:

- ●   IEEE SA PREPAR policy
- ●   IEEE SA Copyright Policy
- ●   IEEE SA Participation Policy

Chair asked if anyone needed these policies reviewed. No one responded.

Chair proceeded to note the following -

- ● Chair reviewed IEEE SA Pre-PAR Patent Policy. See Slide #14.
- ● Chair noted from Slide #16 and noted by participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including but not limited to the IEEE SA Copyright Policy.
- ● Chair reviewed Slide #18 - Participant behavior in IEEE-SA activities is guided by the IEEE Codes of Ethics & Conduct
- ● Chair noted from Slide #19 Participants in the IEEE SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation
- ● Chair noted from Slide #20 – IEEE-SA standards activities shall allow the fair & equitable consideration of all viewpoints

Chair reviewed IEEE 802.3 NEA "Ethernet for AI" Assessment Information on Slide #5.
Chair reviewed Meeting Decorum, Ground Rules, and Important Bylaws, Rules, and References. See Slides #6-9.

Chair gave a brief introduction to the meeting. See Slide #10.

Chair provided overview of future meetings. See Slide #11.

Chair noted that future meetings for all NEA activities had not been planned yet, and future E4AI meetings would be announced. See Slide #10.

Chair reminded group to sign into IMAT.

Presentation #2   **Specifying the optical channel for Ethernet optical PMDs**
Presenters   Guangcan Mi
URL   https://www.ieee802.org/3/ad_hoc/E4AI/public/26_0224/mi_e4ai_01a_260224.pdf

Discussion
There were questions of clarification and discussion on the presentation.

Presentation #3   **Scaling AI Networks with Multicore and Hollow-Core Fiber**
Presenters   Jose Castro
URL   https://www.ieee802.org/3/ad_hoc/E4AI/public/26_0224/castro_e4ai_01_260224.pdf

Discussion
There were questions of clarification and discussion on the presentation.

The chair provided an IMAT reminder.

Presentation #4   **Fiber Overview for datacenter / CDI Links**
Presenters   Duane Robbins
URL   https://www.ieee802.org/3/ad_hoc/E4AI/public/26_0224/ferretti_e4ai_01_260224.pdf

Discussion
There were questions of clarification and discussion on the presentation.
Work has begun in IEC to define a connector for multi-core fiber.

The chair provided an IMAT reminder.

Presentation #5   **Fibers for AI Data Centers - 400 Gbps+ per Lane Applications**
Presenters   Yi Sun
URL   https://www.ieee802.org/3/ad_hoc/E4AI/public/26_0224/sun_e4ai_01_260224.pdf

Discussion
There were questions of clarification and discussion on the presentation.

Presentation #6   **Using MCF and HCF for 1.6TE transmission over single pair fiber**
Presenters   Guangcan Mi
URL   https://www.ieee802.org/3/ad_hoc/E4AI/public/26_0224/mi_e4ai_02a_260224.pdf

Discussion
There were questions of clarification and discussion on the presentation.

Presentation #7   **Analysis of 448Gbps/lane optical signal transmission based on different types of fiber**
Presenters   Xiaojie Fan
URL   https://www.ieee802.org/3/ad_hoc/E4AI/public/26_0224/fan_e4ai_01_260224.pdf

Discussion
There were questions of clarification and discussion on the presentation.

Presentation #8   **Optical shuffle Architectures for Large AI Networks**
Presenters   Jose Castro
URL   https://www.ieee802.org/3/ad_hoc/E4AI/public/26_0224/castro_e4ai_02_260224.pdf

Discussion
There were questions of clarification and discussion on the presentation.

The chair provided another reminder about IMAT.

Meeting adjourned at ≈ 12:25 pm.

IMAT Attendance

Last Name	First Name	Affiliation	Employer
Abbott	John	Corning Incorporated	Retired
Alloin	Laurent	Ciena Corporation	
Bernier	Eric	Huawei Technologies Canada; Huawei Technologies Co., Ltd	Huawei Technologies Canada Co., Ltd.
Brown	Matthew	Qualcomm	Alphawave Semi
Bruckman	Leon	NVIDIA	NVIDIA
Calvin	John	Keysight Technologies	Keysight Technologies
Castro	Jose	Panduit	Panduit
Choudhury	Golam	Lightera	Genuine Optics
Cooke	Mitchell	Qualcomm Incorporated	
D'Ambrosia	John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe	Piers J G	NVIDIA	NVIDIA
Dsilva	Hansel	Amphenol Corporation	
Dube	Kyle	Lightera	
Dudek	Michael	Marvell	Marvell
El-Chayeb	Ahmad	Keysight Technologies Inc	Keysight Technologies Inc
Fan	Xiaojie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ferretti	Vincent	Corning Incorporated	Corning Incorporated
Fischer	Magnus	Kiel University	
Ge	Dawei	China Mobile Communications Group; China Mobile Communications Group	
Ghiasi	Ali	Ghiasi Quantum LLC, MARVELL	Ghiasi Quantum LLC
HE	MICHAEL	TeraHop Pte. Ltd.	
Healey	Adam	Broadcom Inc.	Broadcom Inc.
Hon	Kam Yan	Cisco Systems, Inc.	
Hu	Kangmin	Apple Inc.	
Hu	Runlong	China Mobile Communications Group	China Mobile Communications Group
Huber	Thomas	Nokia	Nokia
Ichijo	Hiroki	Tosoh	Tosoh
Isono	Hideki	Furukawa FITEL Optical Components	Furukawa FITEL Optical Components Limited
Issenhuth	Tom	Huawei Technologies Co., Ltd	Issenhuth Consulting, LLC
Jackson	Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD

Johnson	John	Broadcom	Broadcom Corporation
Kaygusuz	Ahmet	Adhoc Teknoloji	Adhoc Teknoloji
Kiessling	Marcel	Beckhoff Automation	Beckhoff Automation
Kugel	Valery	Juniper Networks, Inc.	
Landry	Gary	Texas Instruments	Texas Instruments Inc.
Law	David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Lessard	Stephane	Ericsson AB	Ericsson AB
Li	Jieyu	China Mobile Communications Group	China Mobile Communications Group
Li	Jing	YOFC	YOFC
Li	Pei-Rong	MediaTek Inc.	MediaTek Inc.
Liu	Cathy	Broadcom	Broadcom Corporation
Lusted	Kent	Synopsys, Inc.	Synopsys, Inc.
Maki	Jeffery	Juniper Networks, Inc.	Hewlett Packard Enterprise
Maniloff	Eric	Ciena Corporation	Ciena Corporation
Mascitto	Marco	Nokia	Infinera Canada Inc.
Mellitz	Richard	Samtec, Inc.	Samtec, Inc.
mi	guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Muhigana	Ernest	Macom Technology Solutions Inc	MACOM Technology Solutions Holdings, Inc.
Muller	Shimon	Enfabrica	Enfabrica Corp.
MURAKAMI	YUKI	1Finity	1Finity
Murty	Ramana	Broadcom Inc.	Broadcom Inc.
Nering	Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Nikolich	Paul	Self Employed	Paul Nikolich
Nowell	Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Opsasnick	Eugene	Broadcom Inc.	Broadcom Inc.
Osorio	Luz	Nokia	
Palkert	Thomas	Samtec, Inc., Macom	Samtec, Inc.
Pan	Chunpo	Broadcom Corporation	
Parsons	Earl	CommScope, Inc.	CommScope, Inc.
Perez De Aranda Alonso	Ruben	Cisco Systems, Inc.	Knowledge Development for POF SL
Rahman	Wahid	MediaTek Inc.	University of California - Berkeley
Ramesh	Sridhar	Maxlinear Inc	MaxLinear
Ransford	Michael	Corning Incorporated	
Rawalgaonkar	Vedashree	INDEPENDENT; Personal	
Robbins	Duane	Corning Incorporated	
Rodes	Roberto	Coherent	II-VI
Sakai	Toshiaki	Socionext	Socionext Inc.
Savi	Olindo	Hubbell Incorporated	Hubbell Incorporated
Shakiba	Mohammad	Huawei Technologies Canada; Huawei Technologies Co., Ltd	Huawei Technologies Canada Co., Ltd.
Simms	William	NVIDIA Corporation	NVIDIA Corporation
Sokolovsky	Alex	Huawei Technologies Co., Ltd	
Sommers	Scott	Molex Incorporated	Molex LLC
Specht	Johannes	Self	Self Employed
Sun	Yi	Lightera	Lightera

Swenson	Norman	Norman Swenson Consulting; Point2 Technology Inc., Nokia	Norman Swenson Consulting
Tartaglia	Antonio	Ericsson AB	Ericsson AB
Torres	Luisma	KD	Knowledge Development for POF SL
Wang	Haojie	China Mobile	China Mobile Communications Corporation (CMCC)
Wang	Xiaofeng	Qualcomm Incorporated	Qualcomm Incorporated
WANG	Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wu	Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Yildiz	Mucahit	Adhoc Teknoloji	
Yin	Shuang	Google	
Yu	Rang-Chen	Innolight Technology Corproation	Innolight Technology Corproation
Zhuang	Shu	Anritsu Company	